

## **Gas Gauge IC**

#### **Features**

- ➤ Conservative and repeatable measurement of available charge in rechargeable batteries
- Designed for portable equipment such as power tools with high discharge rates
- ➤ Designed for battery pack integration
  - 120µA typical standby current (self-discharge estimation mode)
  - Small size enables implementations in as little as ½ square inch of PCB
- Direct drive of LEDs for capacity display
- ➤ Self-discharge compensation using internal temperature sensor
- ➤ Simple single-wire serial communications port for subassembly testing
- ➤ 16-pin narrow SOIC

## **General Description**

The bq2011J Gas Gauge IC is intended for battery-pack installation to maintain an accurate record of available battery charge. The IC monitors a voltage drop across a sense resistor connected in series between the negative battery terminal and ground to determine charge and discharge activity of the battery. The bq2011J is designed for systems such as power tools with very high discharge rates.

Battery self-discharge is estimated based on an internal timer and temperature sensor. Compensations for battery temperature and rate of charge or discharge are applied to the charge, discharge, and self-discharge calculations to provide available charge information across a wide range of operating conditions. Initial battery capacity is set using the PROG<sub>1-4</sub> and SPFC pins. Actual battery capacity is automatically "learned" in the course of a discharge cycle from full to empty and may be displayed depending on the display mode.

Nominal available charge may be directly indicated using a five-segment LED display. These segments are used to graphically indicate nominal available charge.

The bq2011J supports a simple single-line bidirectional serial link to an external processor (common ground). The bq2011J outputs battery information in response to external commands over the serial link. To support subassembly testing, the outputs may also be controlled by command. The external processor may also overwrite some of the bq2011J gas gauge data registers.

The bq2011J may operate directly from four cells. With the REF output and an external transistor, a simple, inexpensive regulator can be built to provide  $V_{CC}$  from a greater number of cells.

Internal registers include available charge, temperature, capacity, battery ID, and battery status.

#### Pin Connections

#### LCOM 🗖 1 16 □ V<sub>CC</sub> SEG<sub>1</sub>/PROG<sub>1</sub> 2 15 REF SEG<sub>2</sub>/PROG<sub>2</sub> 3 14 D NC SEG PROG₃ 4 13 🗆 DQ SEG,/PROG 4 5 12 RBI SEG<sub>5</sub> ☐ 6 11 D SB SPFC ☐ 7 10 DISP 9 🗆 SR V <sub>SS</sub> □ 8 16-Pin Narrow SOIC PN-90

#### **Pin Names**

LCOM	LED common output	REF	Voltage reference output
$SEG_{1}/PROG_{1}$	LED segment 1/ Program 1 input	NC	No connect
SEG <sub>2</sub> /PROG <sub>2</sub>	LED segment 2 / Program 2 input	DQ	Serial communications input/output
ara arroa	1	RBI	Register backup input
SEG <sub>3</sub> /PROG <sub>3</sub>	LED segment 3/ Program 3 input	SB	Battery sense input
SEG <sub>4</sub> /PROG <sub>4</sub>	LED segment 4/ Program 4 input	DISP	Display control input
ana.	•	SR	Sense resistor input
SEG <sub>5</sub>	LED segment 5	$V_{CC}$	3.0-6.5V
SPFC	Programmed full count selection input	$V_{SS}$	Negative battery terminal

### **Pin Descriptions**

#### LCOM LED common

Open-drain output switches  $V_{CC}$  to source current for the LEDs. The switch is off during initialization to allow reading of PROG<sub>1-4</sub> pullup or pull-down program resistors. LCOM is high impedance when the display is off.

#### SEG<sub>1</sub>-SEG<sub>5</sub>

#### LED display segment outputs

Each output may activate an LED to sink the current sourced from MODE, the battery, or  $\ensuremath{V_{\mathrm{CC}}}.$ 

## PROG<sub>1</sub>- Programmed full count selection inputs PROG<sub>4</sub> (dual function with SEG<sub>1</sub> - SEG<sub>4</sub>)

These three-level input pins define the programmed full count (PFC) in conjunction with SPFC pin, define the display mode and enable or disable self-discharge.

#### SPFC Programmed full count selection input

This three-level input pin along with PROG<sub>1-3</sub> define the programmed full count (PFC) thresholds and scale selections described in Table 1 and Table 2. The state of the SPFC pin is only read immediately after a reset condition.

#### SR Sense resistor input

The voltage drop ( $V_{SR}$ ) across the sense resistor Rs is monitored and integrated over time to interpret charge and discharge activity. The SR input is tied to the low side of the sense resistor and battery pack ground (see Figure 1.  $V_{SR} > V_{SS}$  indicates discharge, and  $V_{SR} < V_{SS}$  indicates charge. The effective voltage drop,  $V_{SRO}$ , as seen by the bq2011J is  $V_{SR} + V_{OS}$  (see Table 4).

#### NC No connect

#### **DISP** Display control input

 $\overline{DISP}$  floating allows the LED display to be active during charge and discharge if  $V_{SRO} <$  -1mV (charge) or  $V_{SRO} > 2mV$  (discharge). Transitioning  $\overline{DISP}$  low activates the display for  $4\pm0.5$  seconds.

#### SB Secondary battery input

This input monitors the single-cell voltage potential through a high-impedance resistive divider network for the end-of-discharge voltage (EDV) threshold and maximum cell voltage (MCV).

#### RBI Register backup input

This input is used to provide backup potential to the bq2011J registers during periods when  $V_{\rm CC} \le 3V$ . A storage capacitor should be connected to RBI.

#### DQ Serial I/O pin

This is an open-drain bidirectional pin.

#### REF Voltage reference output for regulator

REF provides a voltage reference output for an optional micro-regulator.

#### V<sub>CC</sub> Supply voltage input

#### Vss Ground

# Functional Description General Operation

The bq2011J determines battery capacity by monitoring the amount of charge input to or removed from a rechargeable battery. The bq2011J measures discharge and charge currents, estimates self-discharge, monitors the battery for low-battery voltage thresholds, and compensates for temperature and charge/discharge rates. The charge measurement is made by monitoring the voltage across a small-value series sense resistor between the negative battery terminal and ground. The available battery charge is determined by monitoring this voltage over time and correcting the measurement for the environmental and operating conditions.

Figure 1 shows a typical battery pack application of the bq2011J using the LED display with absolute mode as a charge-state indicator. The bq2011J can be configured to display capacity in either a relative or an absolute display mode. The relative display mode uses the last measured discharge capacity of the battery as the battery "full" reference. The absolute display mode uses the programmed full count (PFC) as the full reference, forcing each segment of the display to represent a fixed amount of charge. A push-button display feature is available for momentarily enabling the LED display.

The bq2011J monitors the charge and discharge currents as a voltage across a sense resistor (see  $R_{\rm S}$  in Figure 1). A filter between the negative battery terminal and the SR pin may be required if the rate of change of the battery current is too great.

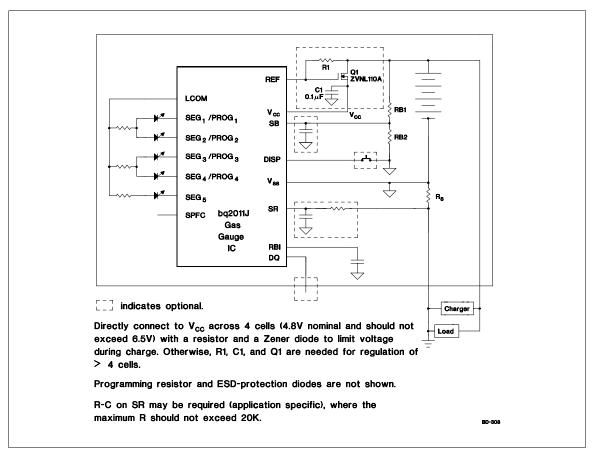


Figure 1. Battery Pack Application Diagram—LED Display,
Absolute Mode

#### Register Backup

The bq2011J RBI input pin is intended to be used with a storage capacitor to provide backup potential to the internal bq2011J registers when  $V_{CC}$  momentarily drops below 3.0V.  $V_{CC}$  is output on RBI when  $V_{CC}$  is above 3.0V.

After  $V_{\rm CC}$  rises above 3.0V, the bq2011J checks the internal registers for data loss or corruption. If data has changed, then the NAC and FULCNT registers are cleared, and the LMD register is loaded with the initial PFC.

#### **Voltage Thresholds**

In conjunction with monitoring  $V_{SR}$  for charge/discharge currents, the bq2011J monitors the single-cell battery potential through the SB pin. The single-cell voltage potential is determined through a resistor-divider network per the following equation:

$$\frac{RB_1}{RB_2} \, = \, N-1$$

where N is the number of cells,  $RB_1$  is connected to the positive battery terminal, and  $RB_2$  is connected to the negative battery terminal. The single-cell battery voltage is monitored for the end-of-discharge voltage (EDV) and for maximum cell voltage (MCV). The EDV threshold level is used to determine when the battery has reached an "empty" state, and the MCV threshold is used for fault detection during charging. The EDV and MCV thresholds for the bq2011J are fixed at:

$$\begin{aligned} V_{EDV} &= 0.90V \\ V_{MCV} &= 2.00V \end{aligned}$$

EDV detection is disabled if the discharge is at a rate equivalent to or greater than 6C (OVLD flag = 1) EDV detection is re-enabled approximately one second after the discharge falls below a rate equivalent to less than 6C (OVLD flag = 0).

#### Reset

The bq2011J recognizes a valid battery whenever  $V_{SB}$  is greater than 0.1V typical.  $V_{SB}$  rising from below 0.25V resets the device. Reset can also be accomplished with a command over the serial port as described in the Reset Register section.

#### **Temperature**

The bq2011J internally determines the temperature in  $10^{\circ}\text{C}$  steps centered from -35°C to +85°C. The temperature steps are used to adapt charge and discharge rate compensations, self-discharge counting, and available charge display translation. The temperature range is available over the serial port in  $10^{\circ}\text{C}$  increments as shown in the following chart:

TMPGG (hex)	Temperature Range
0x	< -30°C
1x	-30°C to -20°C
2x	-20°C to -10°C
3x	-10°C to 0°C
4x	0°C to 10°C
5x	10°C to 20°C
6x	20°C to 30°C
7x	30°C to 40°C
8x	40°C to 50°C
9x	50°C to 60°C
Ax	60°C to 70°C
Bx	70°C to 80°C
Сх	> 80°C

### **Layout Considerations**

The bq2011J measures the voltage differential between the SR and  $V_{SS}$  pins.  $V_{OS}$  (the offset voltage at the SR pin) is greatly affected by PC board layout. For optimal results, the PC board layout should follow the strict rule of a single-point ground return. Sharing high-current ground with small signal ground causes undesirable noise on the small signal nodes. Additionally:

- The capacitors (SB and  $V_{CC}$ ) should be placed as close as possible to the SB and  $V_{CC}$  pins, respectively, and their paths to  $V_{SS}$  should be as short as possible. A high-quality ceramic capacitor of  $0.1\mu f$  is recommended for  $V_{CC}$ .
- The sense resistor (R<sub>S</sub>) should be as close as possible to the bq2011J.
- The R-C on the SR pin should be located as close as possible to the SR pin. The maximum R should not exceed 20K.

#### **Gas Gauge Operation**

The operational overview diagram in Figure 2 illustrates the operation of the bq2011J. The bq2011J accumulates a measure of charge and discharge currents, as well as an estimation of self-discharge. Charge and discharge currents are temperature and rate compensated, whereas self-discharge is only temperature compensated.

The main counter, Nominal Available Charge (NAC), represents the available battery capacity at any given time. Battery charging increments the NAC register, while battery discharging and self-discharge decrement

the NAC register and increment the DCR (Discharge Count Register).

The Discharge Count Register (DCR) is used to update the Last Measured Discharge (LMD) register only if a complete battery discharge from full to empty occurs without any partial battery charges. Therefore, the bq2011J adapts its capacity determination based on the actual conditions of discharge.

The battery's initial capacity is equal to the Programmed Full Count (PFC) shown in Table 1. Until LMD is updated, NAC counts up to but not beyond this threshold during subsequent charges. This approach allows the gas gauge to be charger-independent and compatible with any type of charge regime.

## 1. Last Measured Discharge (LMD) or learned battery capacity:

LMD is the last measured discharge capacity of the battery. On initialization (application of  $V_{CC}$  or battery replacement), LMD = PFC. During subsequent discharges, the LMD is updated with the latest measured capacity in the Discharge Count Register (DCR) representing a discharge from full to below EDV. A qualified discharge is necessary for a capacity transfer from the DCR to the LMD register. The LMD also serves as the 100% reference threshold used by the relative display mode.

#### 2. Programmed Full Count (PFC) or initial battery capacity:

The initial LMD and gas gauge rate values are programmed by using PFC. The PFC also provides

the 100% reference for the absolute display mode. The bq2011J is configured for a given application by selecting a PFC value from Table 1. The correct PFC may be determined by multiplying the rated battery capacity in mAh by the sense resistor value:

Battery capacity (mAh) \* sense resistor ( $\Omega$ ) =

#### PFC (mVh)

Selecting a PFC slightly less than the rated capacity for absolute mode provides capacity above the full reference for much of the battery's life.

#### Example: Selecting a PFC Value

#### Given:

Sense resistor =  $0.002\Omega$ Number of cells = 6Capacity = 1800mAh, NiCd cells Current range = 1A to 80A Relative display mode Self-discharge =  $\frac{C}{80}$ Voltage drop across sense resistor = 2mV to 160mV

#### Therefore:

 $1800 mAh * 0.002 \Omega = 3.6 mVh$ 

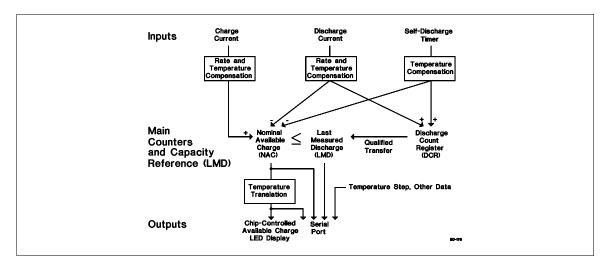


Figure 2. Operational Overview

#### Select:

PFC = 35840 counts or 3.39mVh SPFC = Z (float) PROG1, PROG2 = H or Z PROG3 = L PROG4 = H or Z

The initial full battery capacity is 3.39 mVh (1695mAh) until the bq2011J "learns" a new capacity with a qualified discharge from full to EDV.

#### 3. Nominal Available Charge (NAC):

NAC counts up during charge to a maximum value of LMD and down during discharge and self discharge to 0. NAC is reset to 0 on initialization and on the first valid charge following discharge to EDV. To prevent overstatement of charge during periods of overcharge, NAC stops incrementing when NAC = LMD.

**Note:** NAC is set to the value in LMD when PROG<sub>4</sub> is pulled low during a reset.

Table 1. bq2011J Programmed Full Count mVh Selections

Programmed Full Count (PFC)	mVh	Scale	Display Mode	SPFC	PROG <sub>1</sub>	PROG <sub>2</sub>	PROG₃
40192	3.81	1/10560		Н	H or Z	H or Z	H or Z
32256	3.05	1/10560		Z	H or Z	H or Z	H or Z
28928	2.74	1/10560	Absolute	L	H or Z	H or Z	H or Z
25856	2.45	1/10560		Н	L	H or Z	H or Z
35840	3.39	1/10560		Z	L	H or Z	H or Z
23296	2.21	1/10560		L	L	H or Z	H or Z

**Table 2. Programmed Self-Discharge** 

PROG <sub>4</sub>	NAC Reset Value	Self-Discharge		
H or Z	NAC = 0	Enabled		
L	NAC = PFC	Disabled		

#### 4. Discharge Count Register (DCR):

The DCR counts up during discharge independent of NAC and could continue increasing after NAC has decremented to 0. Prior to NAC = 0 (empty battery), both discharge and self-discharge increment the DCR. After NAC = 0, only discharge increments the DCR. The DCR resets to 0 when NAC = LMD. The DCR does not roll over but stops counting when it reaches FFFFh.

The DCR value becomes the new LMD value on the first charge after a valid discharge to  $V_{\rm EDV}$  if:

No valid charge initiations (charges greater than 256 NAC counts; or 0.006-0.01C) occurred during the period between NAC = LMD and EDV detected.

The self-discharge count is not more than 4096 counts (8% to 18% of PFC, specific percentage threshold determined by PFC).

The temperature is  $\geq 0^{\circ}C$  when the EDV level is reached during discharge.

The valid discharge flag (VDQ) indicates whether the present discharge is valid for LMD update.

#### **Charge Counting**

Charge activity is detected based on a negative voltage on the  $V_{SR}$  input. If charge activity is detected, the bq2011J increments NAC at a rate proportional to  $V_{SRO} \, (V_{SR} + V_{OS})$  and, if enabled, activates an LED display if  $V_{SRO} < \text{-}1\text{mV}$ . Charge actions increment the NAC after compensation for charge rate and temperature.

The bq2011J determines a valid charge activity sustained at a continuous rate equivalent to  $V_{SRO}<$  -400 $\mu V.$  A valid charge equates to a sustained charge activity greater than 256 NAC counts. Once a valid charge is detected, charge counting continues until  $V_{SRO}$  rises above -400 $\mu V.$ 

#### **Discharge Counting**

All discharge counts where  $V_{SRO} > 500\mu V$  cause the NAC register to decrement and the DCR to increment. Exceeding the fast discharge threshold (FDQ) if the rate is equivalent to  $V_{SRO} > 2mV$  activates the display, if enabled. The display becomes inactive after  $V_{SRO}$  falls below 2mV.

#### Self-Discharge Estimation

The bq2011J continuously decrements NAC and increments DCR for self-discharge based on time and temperature. The self-discharge count rate is programmed to be a nominal  $\frac{1}{80}$  \* NAC rate per day or disabled per Table 2. This is the rate for a battery whose

temperature is between 20°-30°C. The NAC register cannot not be decremented below 0.

### **Count Compensations**

The bq2011J determines fast charge when the NAC updates at a rate of  $\geq 2$  counts/sec. Charge and discharge activity is compensated for temperature and charge/discharge rate before updating the NAC and/or DCR. Self-discharge estimation is compensated for temperature before updating the NAC or DCR.

#### **Charge Compensation**

Two charge efficiency factors are used for trickle charge and fast charge. Fast charge is defined as a rate of charge resulting in  $\geq 2$  NAC counts/sec ( $\geq 0.15C$  to 0.32C depending on PFC selections; see Table 1). The compensation defaults to the fast charge factor until the actual charge rate is determined.

Temperature adapts the charge rate compensation factors over three ranges between nominal, warm, and hot temperatures. The compensation factors are shown below

Charge Temperature	Trickle Charge Compensation	Fast Charge Compensation		
<30°C	0.80	0.95		
30-40°C	0.75	0.90		
> 40°C	0.65	0.80		

#### **Discharge Compensation**

Corrections for the rate of discharge are made by adjusting an internal compensation factor. This factor is based upon the number of NAC counts per second. The actual "C" rate may be calculated by using the following formula:

$$C_{RATE} = \frac{K}{N * LMD}$$

where:

K = 66,000

N = Number of samples

LMD = Contents of address 05h

The compensation factors during discharge are:

Samples	Discharge Compensation Factor	Effective CRATE LMD = 9Dh
N > 70	1.00	$C_{RATE} < 6.0C$
70 ≥ N > 35	1.05	$6.0C \leq C_{RATE} < \\ 12.0C$
$35 \geq N > 23$	1.15	$12.0C \le C_{RATE} < 18.0C$
N ≤ 23	1.25	$C_{RATE} \ge 18.0C$

Temperature compensation during discharge also takes place. At lower temperatures, the compensation factor increases by 0.05 for each  $10^{\circ}\text{C}$  temperature step below  $10^{\circ}\text{C}$ .

Comp. factor = 
$$1.00 + (0.05 * N)$$

Where N = number of  $10^{\circ}C$  steps below  $10^{\circ}C$  and  $C_{RATE} < 6.0C$ .

#### For example:

T > 10°C: Nominal compensation, N = 0

 $0^{\circ}$ C < T <  $10^{\circ}$ C: N = 1 (i.e., 1.00 becomes 1.05)

 $-10^{\circ}\text{C} < \text{T} < 0^{\circ}\text{C}$ : N = 2 (i.e., 1.00 becomes 1.10)

 $-20^{\circ}$ C < T <  $-10^{\circ}$ C: N = 3 (i.e., 1.00 becomes 1.15)

-20°C < T < -30°C: N = 4 (i.e., 1.00 becomes 1.20)

#### Self-Discharge Compensation

The self-discharge compensation is programmed for a nominal rate of  ${}^{1}\!/_{80}$  \* NAC per day or disabled. This is the rate for a battery within the 20–30°C temperature range (TMPGG = 6x). This rate varies across 8 ranges from <10°C to >70°C, doubling with each higher temperature step (10°C). See Table 3.

**Table 3. Self-Discharge Compensation** 

Temperature Range	Self-Discharge Compensation Typical Rate/Day
< 10°C	NAC/ <sub>320</sub>
10-20°C	NAC/ <sub>160</sub>
20-30°C	NAC/80
30-40°C	NAC/40
40-50°C	NAC/ <sub>20</sub>
50–60°C	NAC/10
60-70°C	NAC/ <sub>5</sub>
> 70°C	NAC <sub>/2.5</sub>

### **Error Summary**

#### **Capacity Inaccurate**

The LMD is susceptible to error on initialization or if no updates occur. On initialization, the LMD value includes the error between the programmed full capacity and the actual capacity. This error is present until a valid discharge occurs and LMD is updated (see "4. Discharge Count Register" on the previous page). The other cause of LMD error is battery wear-out. As the battery ages, the measured capacity must be adjusted to account for changes in actual battery capacity.

A Capacity Inaccurate counter (CPI) is maintained and incremented each time a valid charge occurs and is reset whenever LMD is updated from the DCR. The counter does not wrap around but stops counting at 255. The capacity inaccurate flag (CI) is set if LMD has not been updated following 64 valid charges.

#### **Current-Sensing Error**

Table 3 illustrates the current-sensing error as a function of  $V_{SR}.$  A digital filter eliminates charge and discharge counts to the NAC register when  $V_{SRO}$  ( $V_{SR}$  +  $V_{OS}$ ) is between -400 $\mu V$  and 500 $\mu V.$ 

Table 4. bq2011J Current-Sensing Errors

Symbol	Parameter	Typical	Maximum	Units	Notes
Vos	Offset referred to V <sub>SR</sub>	± 50	± 150	μV	$\overline{\text{DISP}} = V_{\text{CC}}.$
INL	Integrated non-linearity error	± 2	± 4	%	Add 0.1% per °C above or below 25°C and 1% per volt above or below 4.25V.
INR	Integrated non- repeatability error	± 1	± 2	%	Measurement repeatability given similar operating conditions.

### Communicating With the bq2011J

The bq2011J includes a simple single-pin (DQ plus return) serial data interface. A host processor uses the interface to access various bq2011J registers. Battery characteristics may be easily monitored by adding a single contact to the battery pack. The open-drain DQ pin on the bq2011J should be pulled up by the host system, or may be left floating if the serial interface is not used.

The interface uses a command-based protocol, where the host processor sends a command byte to the bq2011J. The command directs the bq2011J to either store the next eight bits of data received to a register specified by the command byte or output the eight bits of data specified by the command byte.

The communication protocol is asynchronous returnto-one. Command and data bytes consist of a stream of eight bits that have a maximum transmission rate of 333 bits/sec. The least-significant bit of a command or data byte is transmitted first. The protocol is simple enough that it can be implemented by most host processors using either polled or interrupt processing. Data input from the bq2011J may be sampled using the pulse-width capture timers available on some microcontrollers.

Communication is normally initiated by the host processor sending a BREAK command to the bq2011J. A BREAK is detected when the DQ pin is driven to a logic-low state for a time,  $t_B$  or greater. The DQ pin should then be returned to its normal ready-high logic state for a time,  $t_{BR}$ . The bq2011J is now ready to receive a command from the host processor.

The return-to-one data bit frame consists of three distinct sections. The first section is used to start the transmission by either the host or the bq2011J taking the DQ pin to a logic-low state for a period,  $t_{\rm STRH,B}$ . The next section is the actual data transmission, where the data should be valid by a period,  $t_{\rm DSU}$ , after the negative edge used to start communication. The data should be held for a period,  $t_{\rm DV}$ , to allow the host or bq2011J to sample the data bit.

The final section is used to stop the transmission by returning the DQ pin to a logic-high state by at least a period,  $t_{\rm SSU}$ , after the negative edge used to start communication. The final logic-high state should be held until a period,  $t_{\rm SV}$ , to allow time to ensure that the bit transmission was stopped properly. The timings for data and break communication are given in the serial communication timing specification and illustration sections.

Communication with the bq2011J is always performed with the least-significant bit being transmitted first. Figure 3 shows an example of a communication sequence to read the bq2011J NAC register.

### bq2011J Registers

The bq2011J command and status registers are listed in Table 5 and described below.

#### Command Register (CMDR)

The write-only CMDR register is accessed when eight valid command bits have been received by the bq2011J. The CMDR register contains two fields:

- W/R bit
- Command address

The  $W/\overline{R}$  bit of the command register is used to select whether the received command is for a read or a write function.

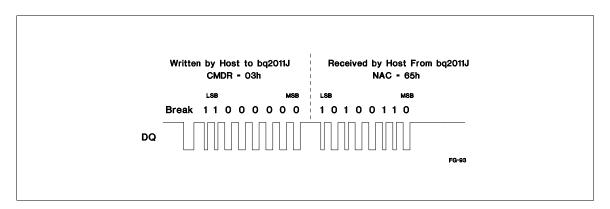


Figure 3. Typical Communication With the bq2011J

Table 5. bq2011J Command and Status Registers

				Control Field							
Symbol	Register Name	Loc. (hex)	Read/ Write	7(MSB)	6	5	4	3	2	1	0(LSB)
CMDR	Command register	00h	Write	W/R	AD6	AD5	AD4	AD3	AD2	AD1	AD0
FLGS1	Primary status flags register	01h	Read	CHGS	BRP	MCV	CI	VDQ	n/u	EDV	n/u
TMPGG	Temperature and gas gauge register	02h	Read	TMP3	TMP2	TMP1	TMP0	GG3	GG2	GG1	GG0
NACH	Nominal available charge high byte register	03h	R/W	NACH7	NACH6	NACH5	NACH4	NACH3	NACH2	NACH1	NACH0
NACL	Nominal available charge low byte register	17h	Read	NACL7	NACL6	NACL5	NACL4	NACL3	NACL2	NACL1	NACL0
BATID	Battery identification register	04h	R/W	BATID7	BATID6	BATID5	BATID4	BATID3	BATID2	BATID1	BATID0
LMD	Last measured discharge register	05h	R/W	LMD7	LMD6	LMD5	LMD4	LMD3	LMD2	LMD1	LMD0
FLGS2	Secondary status flags register	06h	Read	CR	DR2	DR1	DR0	n/u	n/u	n/u	OVLD
СРІ	Capacity inaccurate count register	09h	Read	CPI7	CPI6	CPI5	CPI4	CPI3	CPI2	CPI1	CPI0
OCTL	Output control register	0ah	Write	1	OC5	OC4	осз	OC2	OC1	n/u	OCE
FULCNT	Full count register	0bh	Read	FUL7	FUL6	FUL5	FUL4	FUL3	FUL2	FUL1	FUL0
RST	Reset register	39h	Write	RST	0	0	0	0	0	0	0

**Note:** n/u = not used

#### The $W/\overline{R}$ values are:

CMDR Bits									
7	6	5	4	3	2	1	0		
W/R	-	-	-	-	-	-	-		

#### Where $W/\overline{R}$ is:

- The bq2011J outputs the requested register contents specified by the address portion of CMDR.
- 1 The following eight bits should be written to the register specified by the address portion of CMDR.

The lower seven-bit field of CMDR contains the address portion of the register to be accessed. Attempts to write to invalid addresses are ignored.

CMDR Bits										
7	6	5	4	3	2	1	0			
-	AD6	AD5	AD4	AD3	AD2	AD1	AD0 (LSB)			

#### **Primary Status Flags Register (FLGS1)**

The read-only FLGS1 register (address=01h) contains the primary bq2011J flags.

The *charge status* flag (CHGS) is asserted when a valid charge rate is detected. Charge rate is deemed valid when  $V_{SRO} < -400 \mu V$ . A  $V_{SRO}$  of greater than-  $400 \mu V$  or discharge activity clears CHGS.

The CHGS values are:

FLGS1 Bits									
7	6	5	4	3	2	1	0		
CHGS	•	-	-	-	1	1	- 1		

#### Where CHGS is:

- 0 Either discharge activity detected or  $V_{SRO} > -400 \mu V$
- $1 \qquad V_{SRO} < -400 \mu V$

The *battery replaced* flag (BRP) is asserted whenever the potential on the SB pin (relative to  $V_{SS}$ ),  $V_{SB}$ , rises above 0.1V and determines the internal registers have been corrupted. The BRP flag is also set when the bq2011J is reset (see the RST register description). BRP is cleared if either the bq2011J is charged until NAC = LMD or discharged until EDV is reached. BRP = 1 signifies that the device has been reset.

#### The BRP values are:

FLGS1 Bits							
7	6	5	4	3	2	1	0
-	BRP	-	-	-	-	-	-

#### Where BRP is:

- 0 bq2011J is charged until NAC = LMD or discharged until the EDV flag is asserted
- $1 \hspace{0.5cm} SB \hspace{0.1cm} rising \hspace{0.1cm} from \hspace{0.1cm} below \hspace{0.1cm} 0.1V, \hspace{0.1cm} or \hspace{0.1cm} a \hspace{0.1cm} serial \hspace{0.1cm} port \hspace{0.1cm} initiated \hspace{0.1cm} reset \hspace{0.1cm} has \hspace{0.1cm} occurred$

The *maximum cell voltage* flag (MCV) is asserted whenever the potential on the SB pin (relative to V<sub>SS</sub>) is above 2.0V. The MCV flag is asserted until the condition causing MCV is removed.

#### The MCV values are:

	FLGS1 Bits							
7	6	5	4	3	2	1	0	
-	-	MCV	-	-	-	-	-	

#### Where MCV is:

- $0 \qquad V_{SB} < 2.0 V$
- $1 V_{SB} > 2.0V$

The *capacity inaccurate* flag (CI) is used to warn the user that the battery has been charged a substantial number of times since LMD has been updated. The CI flag is asserted on the 64th charge after the last LMD update or when the bq2011J is reset. The flag is cleared after an LMD update.

#### The CI values are:

	FLGS1 Bits								
7	6	5	4	3	2	1	0		
-	-	-	CI	-	-	-	-		

#### Where CI is:

- 0 When LMD is updated with a valid full discharge
- $1 \qquad \text{After the 64th valid charge action with no LMD} \\ \text{updates or the bq2011J is reset}$

The *valid discharge* flag (VDQ) is asserted when the bq2011J is discharged from NAC=LMD. The flag remains set until either LMD is updated or one of three actions that can clear VDQ occurs:

- The self-discharge count register (SDCR) has exceeded the maximum acceptable value (4096 counts) for an LMD update.
- $\blacksquare$  A valid charge action equal to 256 NAC counts with  $V_{SRO}\,{<}\,{-}400\mu V.$
- The EDV flag was set at a temperature below 0°C

The VDQ values are:

FLGS1 Bits							
7	6	5	4	3	2	1	0
-	-	-	-	VDQ	-	-	-

Where VDQ is:

- 0 SDCR  $\geq$  4096, subsequent valid charge action detected, or EDV is asserted with the temperature less than 0°C
- 1 On first discharge after NAC = LMD

The *end-of-discharge warning* flag (EDV) warns the user that the battery is empty. SEG1 blinks at a 4Hz rate. EDV detection is disabled if OVLD = 1. The EDV flag is latched until a valid charge has been detected.

The EDV values are:

FLGS1 Bits							
7	6	5	4	3	2	1	0
-	-	-	-	-	-	EDV	-

Where EDV is:

- 0 Valid charge action detected and  $V_{SB} \ge 0.90V$
- 1  $V_{SB} < 0.90V$  providing that OVLD = 0

## Temperature and Gas Gauge Register (TMPGG)

The read-only TMPGG register (address=02h) contains two data fields. The first field contains the battery temperature. The second field contains the available charge from the battery.

TMPGG Temperature Bits							
7	6	5	4	3	2	1	0
TMP3	TMP2	TMP1	TMP0	-	-	-	

The bq2011J contains an internal temperature sensor. The temperature is used to set charge and discharge efficiency factors as well as to adjust the self-discharge coefficient. The temperature register contents may be translated as shown below.

TMP3	TMP2	TMP1	TMP0	Temperature
0	0	0	0	T < -30°C
0	0	0	1	-30°C < T < -20°C
0	0	1	0	-20°C < T < -10°C
0	0	1	1	-10°C < T < 0°C
0	1	0	0	0°C < T < 10°C
0	1	0	1	10°C < T < 20°C
0	1	1	0	20°C < T < 30°C
0	1	1	1	30°C < T < 40°C
1	0	0	0	40°C < T < 50°C
1	0	0	1	50°C < T < 60°C
1	0	1	0	60°C < T < 70°C
1	0	1	1	70°C < T < 80°C
1	1	0	0	T > 80°C

The bq2011J calculates the available charge as a function of NAC, temperature, and a full reference, either LMD or PFC. The results of the calculation are available via the display port or the gas gauge field of the TMPGG register. The register is used to give available capacity in  $\frac{1}{16}$  increments from 0 to  $\frac{15}{16}$ .

	TMPGG Gas Gauge Bits									
7	6	5	4	3	2	1	0			
-	-	-	-	GG3	GG2	GG1	GG0			

The gas gauge display and the gas gauge portion of the TMPGG register are adjusted for cold temperature dependencies. A piece-wise correction is performed as follows:

Temperature	Available Capacity Calculation
> 0°C	NAC / "Full Reference"
-20°C < T < 0°C	0.75 * NAC / "Full Reference"
< -20°C	0.5 * NAC / "Full Reference"

The adjustment between >  $0^{\circ}$ C and  $-20^{\circ}$ C < T <  $0^{\circ}$ C has a  $4^{\circ}$ C hysteresis.

#### Nominal Available Charge Register (NAC)

The read/write NACH register (address=03h) and the read-only NACL register (address=17h) are the main gas gauging registers for the bq2011J. The NAC registers are incremented during charge actions and decremented during discharge and self-discharge actions. The correction factors for charge/discharge efficiency are applied automatically to NAC.

If  $SEG_5=0$  on reset, then NACH = PFC and NACL = 0. If  $SEG_5=Z$  or H, the NACH and NACL registers are cleared to zero, NACL stops counting when NACL reaches zero. When the bq2011J detects a valid charge, NACL resets to zero; writing to the NAC register affects the available charge counts and, therefore, affects the bq2011J gas gauge operation.

#### **Battery Identification Register (BATID)**

The read/write BATID register (address=04h) is available for use by the system to determine the type of battery pack. The BATID contents are retained as long as  $V_{CC}$  is greater than 2V. The contents of BATID have no effect on the operation of the bq2011J. There is no default setting for this register.

#### Last Measured Discharge Register (LMD)

LMD is a read/write register (address=05h) that the bq2011J uses as a measured full reference. The bq2011J adjusts LMD based on the measured discharge capacity of the battery from full to empty. In this way the bq2011J updates the capacity of the battery. LMD is set to PFC during a bq2011J reset.

#### Secondary Status Flags Register (FLGS2)

The read-only FLGS2 register (address=06h) contains the secondary bq2011J flags.

The *charge rate* flag (CR) is used to denote the fast charge regime. Fast charge is assumed whenever a

charge action is initiated. The CR flag remains asserted if the charge rate does not fall below 2 counts/sec.

The CR values are:

	FLGS2 Bits							
7	6	5	4	3	2	1	0	
CR	-	-	-	-	-	-	-	

Where CR is:

- 0 When charge rate falls below 2 counts/sec
- 1 When charge rate is above 2 counts/sec

The fast charge regime efficiency factors are used when CR=1. When CR=0, the trickle charge efficiency factors are used. The time to change CR varies due to the user-selectable count rates.

The discharge rate flags, DR2-0, are bits 6-4.

	FLGS2 Bits							
7	6	5	4	3	2	1	0	
-	DR2	DR1	DR0	-	-	-		

They are used to determine the present discharge regime as follows:

DR2	DR1	DR0	C <sub>RATE</sub> @LMD = 90h
0	0	0	C <sub>RATE</sub> < 6C
0	0	1	$6C \le C_{RATE} < 12C$
0	1	0	$12C \leq C_{RATE} < 18C$
0	1	1	C <sub>RATE</sub> ≥ 18C

The *overload* flag (OVLD) is asserted when a discharge overload is detected,  $C_{RATE} \geq 6.0C$  for LMD = 90h (see Discharge Compensation, page 8). OVLD remains asserted as long as the condition is valid.

FLGS2 Bits							
7	6	5	4	3	2	1	0
-	_	-	-	-	-	-	OVLD

#### **Full Count Register (FULCNT)**

The read-only FULCNT register (address=0bh) provides the system with a diagnostic of the number of times the battery has been fully charged (NAC = LMD). The number of full occurrences can be determined by multiplying the value in the FULCNT register by 16. Any discharge action

other than self-discharge allows detection of another full occurrence during the next valid charge action.

#### Capacity Inaccurate Count Register (CPI)

The read-only CPI register (address=09h) is used to indicate the number of times a battery has been charged without an LMD update. Because the capacity of a rechargeable battery varies with age and operating conditions, the bq2011J adapts to the changing capacity over time. A complete discharge from full (NAC=LMD) to empty (EDV=1) is required to perform an LMD update assuming there have been no intervening valid charges, the temperature is greater than or equal to 0°C, and the self-discharge counter is less than 4096 counts.

The CPI register is incremented every time a valid charge is detected. The register increments to 255 without rolling over. When the contents of CPI are incremented to 64, the capacity inaccurate flag, CI, is asserted in the FLGS1 register. CPI is reset whenever an update of the LMD register is performed, and the CI flag is also cleared.

#### **Output Control Register (OCTL)**

The write-only OCTL register (address=0ah) provides the system with a means to check the display connections for the bq2011J. The segment drivers may be overwritten by data from OCTL when the least-significant bit of OCTL, OCE, is set. The data in bits  $OC_{5-1}$  of the OCTL register (see Table 5 on page 10 for details) is output onto the segment pins,  $SEG_{5-1}$ , respectively if OCE=1. Whenever OCE is written to 1, the MSB of OCTL should be set to a 1. The OCE register location must be cleared to return the bq2011J to normal operation. OCE may be cleared by either writing the bit to a logic zero via the serial port or by resetting the bq2011J as explained below. **Note:** Whenever the OCTL register is written, the MSB of OCTL should be written to a logic one.

#### Reset Register (RST)

The reset register (address=39h) provides the means to perform a software-controlled reset of the device. A full device reset may be accomplished by first writing LMD (address = 05h) to 00h and then writing the RST register contents from 00h to 80h. Setting any bit other than the most-significant bit of the RST register is **not allowed**, and results in improper operation of the bq2011J.

Resetting the bq2011J sets the following:

- LMD = PFC
- CPI, VDQ, OCE, and NAC = 0 (NAC = PFC when PROG<sub>4</sub> = L)
- CI and BRP = 1

### **Display**

The bq2011J can directly display capacity information using low-power LEDs. If LEDs are used, the segment pins should be tied to  $V_{\rm CC}$ , the battery, or the MODE pin for programming the bq2011J.

The bq2011J displays the battery charge state in either absolute or relative mode. In relative mode, the battery charge is represented as a percentage of the LMD. Each LED segment represents 20% of the LMD.

In absolute mode, each segment represents a fixed amount of charge, based on the initial PFC. In absolute mode, each segment represents 20% of the PFC. As the battery wears out over time, it is possible for the LMD to be below the initial PFC. In this case, all of the LEDs may not turn on, representing the reduction in the actual battery capacity.

The capacity display is also adjusted for the present battery temperature. The temperature adjustment reflects the available capacity at a given temperature but does not affect the NAC register. The temperature adjustments are detailed in the TMPGG register description on page 12.

When  $\overline{DISP}$  is tied to  $V_{CC}$ , the  $SEG_{1-5}$  outputs are inactive. When  $\overline{DISP}$  is left floating, the display becomes active during charge if the NAC registers are counting at a rate equivalent to  $V_{SRO} < -1mV$  or fast discharge if the NAC registers are counting at a rate equivalent to  $V_{SRO} > 2mV$ . When pulled low, the segment output becomes active for 4 seconds,  $\pm 0.5$  seconds.

The segment outputs are modulated as two banks, with segments 1, 3, and 5 alternating with segments 2 and 4. The segment outputs are modulated at approximately 320Hz, with each bank active for 30% of the period.

 $SEG_1$  blinks at a 4Hz rate whenever  $V_{SB}$  has been detected to be below  $V_{EDV}$  to indicate a low-battery condition or NAC is less than 10% of the LMD or PFC, depending on the display mode.

#### Microregulator

The bq2011J can operate directly from 4 cells. To facilitate the power supply requirements of the bq2011J, an REF output is provided to regulate an external low-threshold n-FET. A micropower source for the bq2011J can be inexpensively built using the FET and an external resistor.

## **Absolute Maximum Ratings**

Symbol Parameter		Minimum	Maximum	Unit	Notes
Vcc	Relative to V <sub>SS</sub>		+7.0	V	
All other pins	ther pins Relative to V <sub>SS</sub>		+7.0	V	
Vsr	Relative to V <sub>SS</sub>	-0.3	+7.0	V	Minimum $100\Omega$ series resistor should be used to protect SR in case of a shorted battery (see the bq2011J application note for details).
_	_	0	+70	°C	Commercial
TOPR	Operating temperature	-40	+85	°C	Industrial

Note:

Permanent device damage may occur if **Absolute Maximum Ratings** are exceeded. Functional operation should be limited to the Recommended DC Operating Conditions detailed in this data sheet. Exposure to conditions beyond the operational limits for extended periods of time may affect device reliability.

## DC Voltage Thresholds (TA = TOPR; V = 3.0 to 6.5V)

Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
$V_{\rm EDV}$	End-of-discharge warning	0.87	0.90	0.93	V	SB
V <sub>SRQ</sub>	Valid charge	-	-	-400	μV	V <sub>SR</sub> + V <sub>OS</sub>
V <sub>SRD</sub>	Valid discharge	500	-	-	μV	V <sub>SR</sub> + V <sub>OS</sub>
V <sub>MCV</sub>	Maximum single-cell voltage	1.95	2.0	2.05	V	SB
$V_{\rm BR}$	Battery removed/replaced	-	0.1	0.25	V	SB

**Note:** 

For proper operation of the threshold detection circuit,  $V_{\rm CC}$  must be at least 1.5V greater than the voltage being measured.

## DC Electrical Characteristics (TA = TOPR)

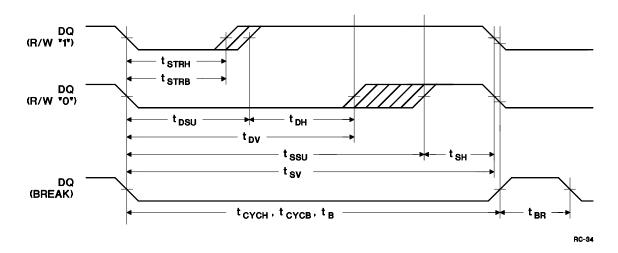
Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
V <sub>C</sub> C	Supply voltage	3.0	4.25	6.5	V	$V_{CC}$ excursion from < 2.0V to $\geq$ 3.0V initializes the unit.
V	Reference at 25°C	5.7	6.0	6.3	V	$I_{REF} = 5\mu A$
$V_{REF}$	Reference at -40°C to +85°C	4.5	-	7.5	V	$I_{REF} = 5\mu A$
R <sub>REF</sub>	Reference input impedance	2.0	5.0	-	ΜΩ	$V_{REF} = 3V$
		-	90	135	μA	$V_{CC} = 3.0V, DQ = 0$
$I_{CC}$	Normal operation	-	120	180	μA	$V_{CC} = 4.25V, DQ = 0$
		-	170	250	μA	$V_{CC} = 6.5V, DQ = 0$
$V_{SB}$	Battery input	0	-	Vcc	V	, ,
R <sub>SBmax</sub>	SB input impedance	10	-	-	ΜΩ	$0 < V_{SB} < V_{CC}$
I <sub>DISP</sub>	DISP input leakage	-	-	5	μA	V <sub>DISP</sub> = V <sub>SS</sub>
I <sub>LCOM</sub>	LCOM input leakage	-0.2	-	0.2	μA	$\overline{\text{DISP}} = V_{\text{CC}}$
I <sub>RBI</sub>	RBI data-retention current	-	-	100	nA	V <sub>RBI</sub> > V <sub>CC</sub> < 3V
R <sub>DQ</sub>	Internal pulldown	500	_	-	ΚΩ	TREE VEC VOI
Vsr	Sense resistor input	-0.3	-	2.0	V	V <sub>SR</sub> > V <sub>SS</sub> = discharge; V <sub>SR</sub> < V <sub>SS</sub> = charge
$R_{SR}$	SR input impedance	10	-	-	$M\Omega$	$-200 mV < V_{SR} < V_{CC}$
VIHPFC	PROG/SPFC logic input high	V <sub>CC</sub> - 0.2	-	-	V	SPFC, PROG <sub>1-4</sub>
VILPFC	PROG/SPFC logic input low	-	-	$V_{SS} + 0.2$	V	SPFC, PROG <sub>1-4</sub>
Vizpfc	PROG/SPFC logic input Z	float	-	float	V	SPFC, PROG <sub>1-4</sub>
I <sub>IHPFC</sub>	PROG/SPFC input high current	-	1.2	-	μΑ	$V_{\rm PFC} = V_{\rm CC}/2$
I <sub>ILPFC</sub>	PROG/SPFC input low current	-	1.2	-	μΑ	$V_{\rm PFC} = V_{\rm CC}/2$
Volsl	SEG <sub>X</sub> output low, low V <sub>CC</sub>	-	0.1	-	V	$\begin{aligned} V_{CC} &= 3V, \ I_{OLS} \leq \ 1.75 mA \\ SEG_1 &- SEG_5 \end{aligned}$
Volsh	SEG <sub>X</sub> output low, high V <sub>CC</sub>	-	0.4	-	V	$\begin{aligned} V_{CC} &= 6.5V, \ I_{OLS} \leq 11.0 mA \\ SEG_1 &- SEG_5 \end{aligned}$
VOHML	LCOM output high, low V <sub>CC</sub>	V <sub>CC</sub> - 0.3	-	-	V	$V_{CC} = 3V$ , $I_{OHLCOM} = -5.25mA$
V <sub>OHMH</sub>	LCOM output high, high V <sub>CC</sub>	V <sub>CC</sub> - 0.6	-	-	V	$V_{CC} = 6.5V$ , $I_{OHLCOM} = -33.0mA$
IOHLCOM	LCOM source current	-33	-	-	mA	At V <sub>OHLCOM</sub> = V <sub>CC</sub> - 0.6V
Iols	$SEG_X$ sink current	11.0	-	-	mA	At $V_{OLSH} = 0.4V$ , $V_{CC} = 6.5V$
I <sub>OL</sub>	Open-drain sink current	5.0	-	-	mA	At $V_{OL} = V_{SS} + 0.3V$ , DQ
Vol	Open-drain output low	-	-	0.5	V	$I_{OL} \le 5mA$ , DQ
$V_{\mathrm{IHDQ}}$	DQ input high	2.5	-	-	V	DQ
$V_{\rm ILDQ}$	DQ input low	-	-	0.8	V	DQ
R <sub>FLOAT</sub>	Float state external impedance	-	5	-	ΜΩ	SPFC, PROG <sub>1-4</sub>

## **Serial Communication Timing Specification** (TA = TOPR)

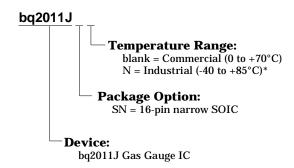
Symbol	Parameter	Minimum	Typical	Maximum	Unit	Notes
tcych	Cycle time, host to bq2011J	3	-	-	ms	See note
$t_{CYCB}$	Cycle time, bq2011J to host	3	-	6	ms	
t <sub>STRH</sub>	Start hold, host to bq2011J	5	-	-	ns	
tstrb	Start hold, bq2011J to host	500	-	-	μs	
t <sub>DSU</sub>	Data setup	-	-	750	μs	
tDH	Data hold	750	-	-	μs	
$t_{DV}$	Data valid	1.50	-	-	ms	
tssu	Stop setup	-	-	2.25	ms	
t <sub>SH</sub>	Stop hold	700	-	-	μs	
tsv	Stop valid	2.95	-	-	ms	
$t_{\rm B}$	Break	3	-	-	ms	
t <sub>BR</sub>	Break recovery	1	-	-	ms	

 $\begin{array}{ll} \textbf{Note:} & \text{The open-drain DQ pin should be pulled to at least $V_{CC}$ by the host system for proper DQ operation.} \\ & DQ \text{ may be left floating if the serial interface is not used.} \\ \end{array}$ 

## **Serial Communication Timing Illustration**

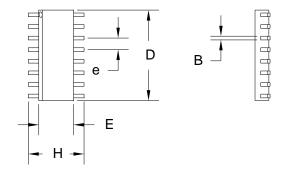


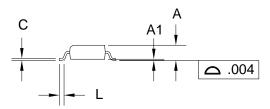
## **Ordering Information**



 $<sup>^{</sup>st}$  Contact factory for availability.

## 16-Pin SOIC Narrow (SN)





## 16-Pin SN (SOIC Narrow)

Dimension	Minimum	Maximum		
Α	0.060	0.070		
A1	0.004	0.010		
В	0.013	0.020		
C	0.007	0.010		
D	0.385	0.400		
E	0.150	0.160		
e	0.045	0.055		
Н	0.225	0.245		
L	0.015	0.035		

All dimensions are in inches.



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